

WHAT IS CLAIMED IS:

1. A method for forming a thin film comprising the steps of:

5 carrying out a predetermined preliminary treatment on a resinous base on which said thin film is to be formed,

carrying out a catalyst applying treatment on said resinous substrate which has been subjected to
10 said preliminary treatment by a catalyzed treatment solution applied with a predetermined amount of fluorine type anionic surfactant, and

carrying out an electroless plating on said resinous substrate which has been subjected to said
15 catalyst-applying treatment to form said thin film.

2. A method for forming a thin film as claimed in claim 1, wherein said resinous base is a liquid crystal polymer film containing no fillers.

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3. A method for forming a thin film as claimed in claim 1, wherein in said catalyst-applying treatment, a series of processes including a sensitization treatment and an activation treatment
25 are continuously repeated a plurality of times.

4. A method for forming a thin film as claimed

in claim 3, wherein said sensitization treatment is carried out by dipping said resinous base which has been subjected to said preliminary treatment in a tin chloride solution applied with the predetermined amount of fluorine type anionic surfactant, and said activation treatment is carried out by dipping said resinous base which has been subjected to said preliminary treatment in a palladium chloride solution applied with the predetermined amount of fluorine type anionic surfactant.

5. A method for forming a thin film as claimed in claim 1, wherein said electroless plating is carried out by dipping said resinous base which has been subjected to said catalyst-applying treatment in a copper plating bath having a relatively low deposition speed.

6. A method for forming a thin film as claimed in claim 5, wherein said copper plating bath is a copper plating bath in which potassium sodium tartrate is contained as a complexing agent.

7. A catalyzed treatment solution comprising:
a sensitization treatment solution containing a predetermined amount of fluorine type anionic surfactant, for carrying out said sensitization

treatment on a base to be subjected to an electroless plating treatment, and

an activation treatment solution containing the predetermined amount of fluorine type anionic
5 surfactant, for carrying out said activation treatment on said base which has been subjected to said sensitization treatment.